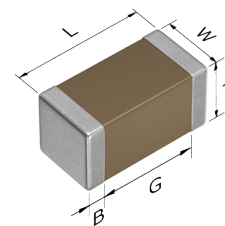


积层贴片陶瓷片式电容器

C1608X5R1V334M080AB

RoHS Reach Halogen Free Pb Free

| | |
|------|---|
| 交货型号 | C1608X5R1V334MT**** |
| 用途 | 一般等级 车载用途时为 CGA3E3X5R1V334M080AB 。 |
| 特点 | General 一般 (~75V) |
| 系列 | C1608 [EIA 0603] |
| 状态 | 量产体制(新设计非推荐) |



尺寸

| | |
|------------|--|
| 长度(L) | 1.60mm ±0.10mm |
| 宽度(W) | 0.80mm ±0.10mm |
| 厚度(T) | 0.80mm ±0.10mm |
| 端子宽度(B) | 0.20mm Min. |
| 端子间隔(G) | 0.30mm Min. |
| 推荐焊盘布局(PA) | 0.70mm to 1.00mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering) |
| 推荐焊盘布局(PB) | 0.80mm to 1.00mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering) |
| 推荐焊盘布局(PC) | 0.60mm to 0.80mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering) |

电气特性

| | |
|-------------|------------|
| 电容 | 330nF ±20% |
| 额定电压 | 35VDC |
| 温度特性 | X5R(±15%) |
| 耗散因数 (Max.) | 5% |
| 绝缘电阻 (Min.) | 1515MΩ |

其他

| | |
|----------|---------------|
| 焊接方法 | 流体 回流 |
| AEC-Q200 | NO |
| 包装形式 | 纸编带 (180mm卷筒) |
| 包装个数 | 4000pcs |

! Images are for reference only and show exemplary products.

! This PDF document was created based on the data listed on the TDK Corporation website.

! All specifications are subject to change without notice.

特性图表 (这是参考数据，并不保证产品的特性。)

Associated Images

